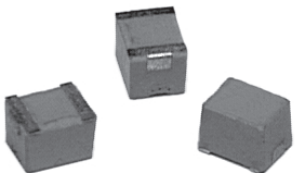
Surface Mount, Molded Inductor



FEATURES

- Molded construction provides superior strength and moisture resistance.
- Tape and reel packaging for automatic handling, 2000/reel, EIA 481.
- Printed marking.
- Compatible with vapor phase and infrared reflow soldering.

STANDARD ELECTRICAL SPECIFICATIONS

IND. (μH)	Q MIN.	TEST FREQ. L & Q (MHz)	SELF-RESONANT FREQ. MIN. (MHz)	DCR MAX. (Ohms)	RATED DC CURRENT (mA)
0.010	15	100.0	2500.0*	0.13	734
0.012	17	100.0	2300.0*	0.14	707
0.015	19	100.0	2100.0*	0.16	661
0.018	21	100.0	1900.0*	0.18	624
0.022	23	100.0	1700.0*	0.20	592
0.027	23	100.0	1500.0*	0.22	564
0.033	25	100.0	1400.0*	0.24	540
0.039	25	100.0	1300.0*	0.27	530
0.047	26	100.0	1200.0*	0.30	483
0.056	26	100.0	1100.0*	0.33	470
0.068	27	100.0	1000.0	0.36	450
0.082	27	100.0	900.0	0.40	450
0.100	28	100.0	700.0	0.44	450

*All SRF values above 1000 MHz are typical minimums.

ELECTRICAL SPECIFICATIONS

Inductance Tolerance: ± 20% for 0.010μH to 0.100μH standard. ± 10% for 0.010μH to 0.100μH and ± 5% for 0.027μH to 0.100μH optional.
Temperature Range: - 55°C to + 125°C.
Core Material: Non-magnetic for 0.010μH to 0.100μH.

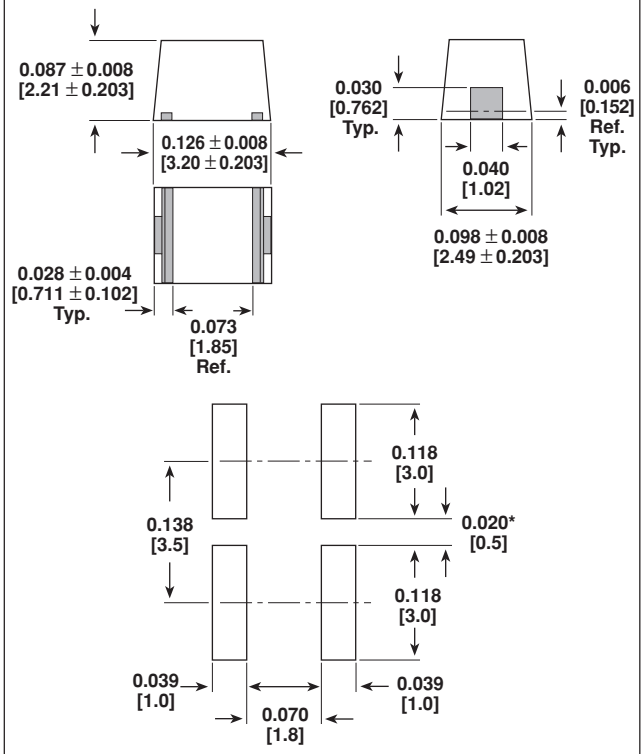
TEST EQUIPMENT

- L, Q, SRF: H/P 4191A RF Impedance Analyzer.
- DCR: Wheatstone bridge or equivalent.

PART MARKING

— Vishay Dale
— Inductance value
— Date code

DIMENSIONS in inches [millimeters]



Guidelines for Parallel Component Printed Circuit Mounting Pads on IMC-1210-100 Chip Inductors

*Recommended minimum spacing between components.

DESCRIPTION

IMC-1210-100	0.010μH	± 20%
MODEL	INDUCTANCE VALUE	INDUCTANCE TOLERANCE

SAP PART NUMBERING GUIDELINES (INTERNAL)

I	M	C	1	2	1	0	S	Y	1	0	N	M	1	0	0
PRODUCT FAMILY			SIZE				PACKAGE CODE		INDUCTANCE VALUE			TOL.	SERIES		

See the end of this data book for conversion tables